Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6717267".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 14:23
L2	2	"6,600,175".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:15
L3	0	2 and power with 25b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:16
L4	0	2 and power same 25b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:16
L5	0	2 and 25b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:16
L6	0	1 and power with 25b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:16
L7	1	1 and power same 25b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:41
L8	2	"5177594".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 17:29
L9	1346	siN with metallic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 17:29

L10	124	siN near2 metallic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 18:17
L11	3167	substrate with pin with board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 18:18
L12	229	substrate with pin with direct$4 with board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 18:18
L13	62	12 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 18:18
L14	9	("20020011662" | "20020074653" | "20020185308" | "5939782" | "6353540" | "6400576" | "6518666" | "6535398" | "6727780").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 18:19
L15	20	("4322778" | "4574255" | "4755910" | "4811082" | "4901136" | "5014114" | "5032896" | "5075253" | "5077639" | "5095402" | "5177670" | "5237204" | "5239198" | "5239448" | "5255431" | "5384691" | "5473513" | "6018463" | "6147876" | "6153290").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 18:21
L16	111	("4064552" | "4081898" | "4104728" | "4177519" | "4495546" | "4567543" | "4598337" | "4672152" | "4744008" | "4754371" | "4843520" | "4926241" | "4933810" | "4937707" | "4967950" | "4982376" | "4987100" | "4990948" | "5028983").PN. OR ("5239448"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 18:24
L17	11	("4612083" | "4939568" | "5138437" | "5191405" | "5202754" | "5239448" | "5266511" | "5380681" | "5489554" | "5579207").PN. OR ("6593645"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 18:27
L18	2419	(257/773).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03

L19	43	L18 and heat with interconnect$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L20	105	("3539705" | "3846166" | "4096623" | "4164461" | "4308090" | "4601915" | "4670091" | "4849070").PN. OR ("5117276").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L21	11	("5117276" | "5444015" | "5798559" | "6245658" | "6255712" | "6277728" | "6386939" | "6403461" | "6614092").PN. OR ("6713835"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L22	1392	L18 and line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L23	361	L18 and line with (power signal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L24	9	("5814844" | "5874754" | "6091088" | "6114767" | "6133079" | "6177709" | "6288447" | "6320234" | "6326651").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L25	10	dummy near interconnection with heat	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L26	6	("5441915" | "5729047" | "5811352").PN. OR ("6717267"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L27	10	dummy near interconnection same heat	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L28	11	dummy near interconnection same heat	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/12 21:03
L29	1	L28 not L27	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/12 21:03
L30	41	dummy near interconnection and heat	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/12 21:03

L31	5	(US-20020058411-$).did. or (US-6800883-$ or US-6717267-$ or US-6913990-$ or US-6664642-$).did.	US-PGPUB; USPAT	OR	ON	2005/12/12 21:03
L32	51	interconnection with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L33	641	(via damascene) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L34	9	(damascene) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L35	4	(via near4 dummy) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L36	0	(interconnect near4 dummy) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L37	0	(interconnect near4 dummy) with heat adj transf$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L38	0	(interconect near4 dummy) with heat adj transf$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L39	0	(interconnecting near4 dummy) with heat adj transf$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03

L40	0	(pattern near4 dummy) with heat adj transf$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L41	0	(pattern near4 dummy) with heat adj transf$4 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L42	10	(pattern near4 dummy) with heat near2 (transfer$3 dissipat$3)and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L43	10	(dummy near4 pattern) with heat near2 (transfer$3 dissipat$3)and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L44	1	(dummy near interconnect$3) with heat near2 (transfer$3 dissipat$3)and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L45	3	(dummy near interconnect$3) with heat near2 (transfer$3 dissipat$3)and (IC integrated adj circuit chip die wafer semiconductor silicon). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L46	409	epoxy with phenolic with curing adj accelerator with inorganic adj filler	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L47	78652	heat with dissipation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L48	4261380	(semiconductor ic integrated adj circuit die chip wafer silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03

L49	172616	power near2 line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L50	220	interconnect with L47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L51	192	L50 and L48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L52	16	L51 and L49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L53	5709	heat with interconnect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L54	2743	L53 and L48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L55	152	L54 and L49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L56	214050	heat with (wir$3 via damascene trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L57	72463	L56 and L48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03

L58	4279	L56 with L47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L59	2485	L58 and L48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L60	102	L59 and L49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L61	33	L60 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L62	55178	(257/7$2).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L63	8561	(257/69$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L64	59536	L62 L63	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L65	10382	L64 and heat with (dissipat$3 remov$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L66	8983	L64 and heat near2 (dissipat$3 remov$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03

L67	5410917	L66 and heat (interconnection via plug wir$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L68	415541	heat with (dissipat$3 remov$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L69	5408490	(interconnection via plug wir$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L70	24902	L68 with L69	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L71	1755	L64 and L70	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L72	235288	heat near2 (dissipat$3 remov$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L73	14025	L72 with L69	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L74	1405	L73 and L62	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L75	900	L73 and L62	USPAT	OR	ON	2005/12/12 21:03
L76	2399	(257/774).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03

L77	46	L73 and L76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L78	3534	(257/758).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L79	32	L73 and L78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L80	4	("5698897" | "5792677").PN. OR ("6242807").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L81	826	(257/760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L82	4	L73 and L81	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L83	360	(257/761).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L84	4	L73 and L82	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L85	5084	(257/76$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L86	18	L73 and L85	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03

L87	9	("5700735" | "5736791" | "5739587" | "5891799" | "5923088" | "6028367" | "6143396" | "6180511" | "6251781").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L88	6	("6028367").URPN.	USPAT	OR	ON	2005/12/12 21:03
L89	12	("5248903" | "5404047" | "5736791" | "5739587" | "5923088" | "5959356").PN. OR ("6028367"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L90	12	("5248903" | "5404047" | "5736791" | "5739587" | "5923088" | "5959356").PN. OR ("6028367"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L91	3	("5354717" "6018193" "20020061614").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L92	2	L91 and heat	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L93	1	"6717267".pn. and power	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L94	478	double with heat with sink	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L95	195	L94 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L96	145	L94 and "257"/$.ccls.	USPAT	OR	ON	2005/12/12 21:03
L97	57	L96 and wire	USPAT	OR	ON	2005/12/12 21:03
L98	143	andujar.xa.	USPAT	OR	ON	2005/12/12 21:03
L99	0	aluminum near2 thermal with expasion with epoxy	USPAT	OR	ON	2005/12/12 21:03
L100	0	aluminum near2 thermal with expasion	USPAT	OR	ON	2005/12/12 21:03
L101	4624	aluminum near2 thermal	USPAT	OR	ON	2005/12/12 21:03
L102	211	(wir$2 with interconnection) with copper	USPAT	OR	ON	2005/12/12 21:03